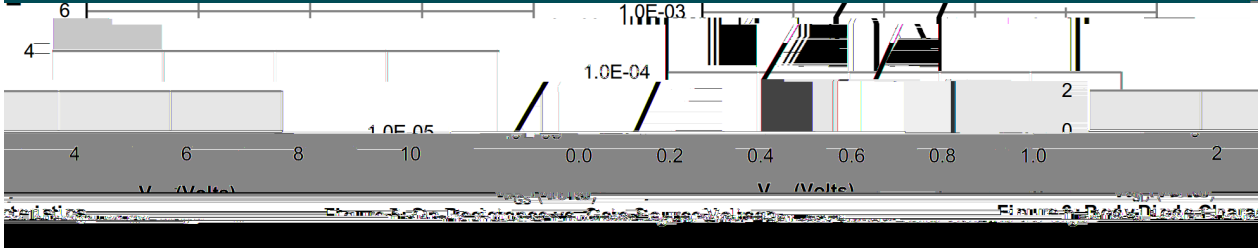
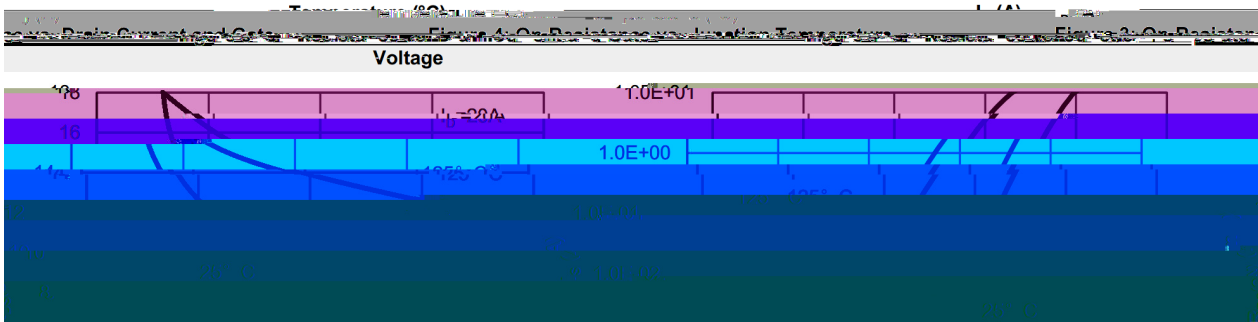
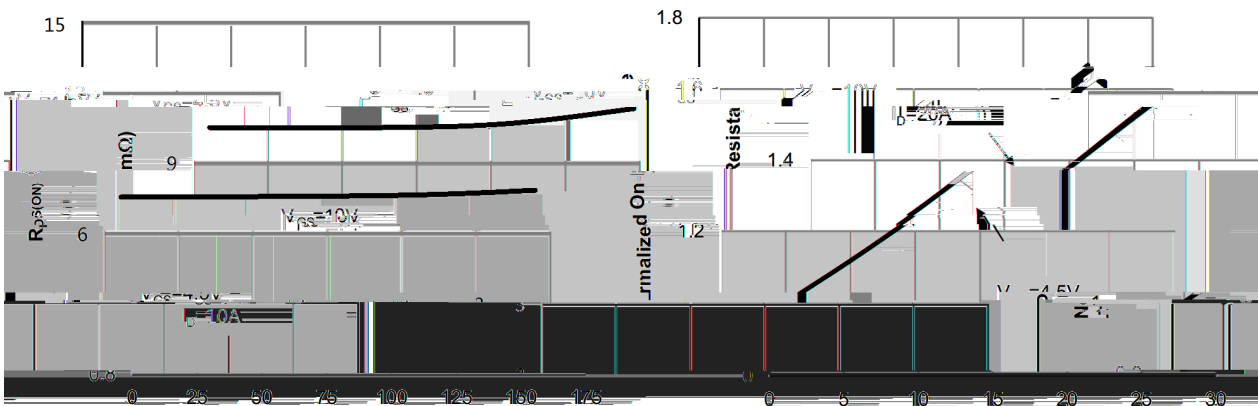
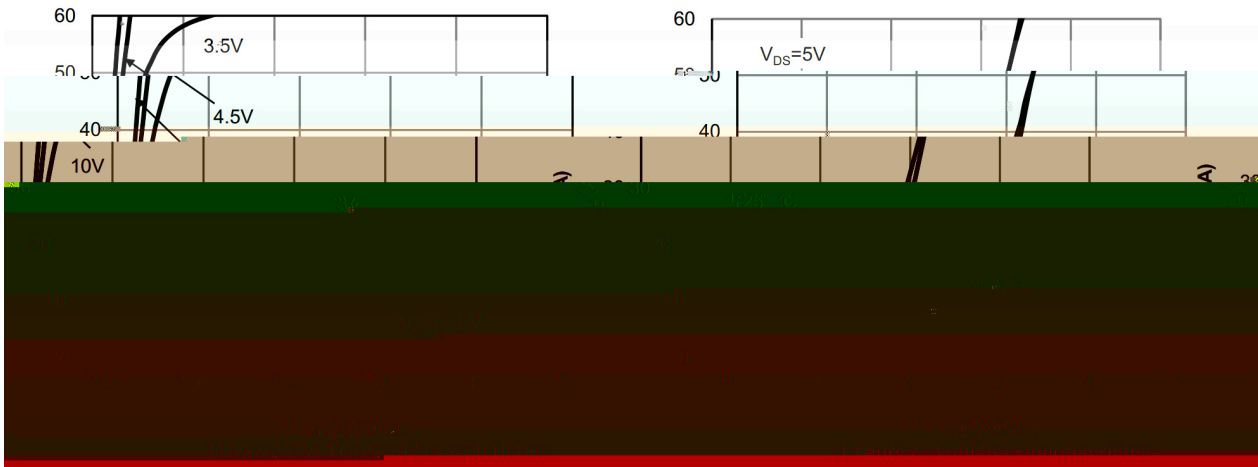


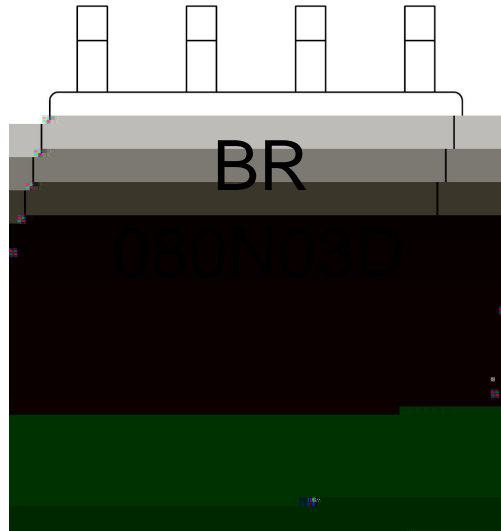
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	16	A
Pulsed Drain Current	I_{DM}	59	A
Power Dissipation	P_D	3.2	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	
Maximum Junction-to-Ambient	$R_{JA}(\text{Steady-State})$	39	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_D=250\mu A$	30	35		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V$ $V_{GS}=0V$			1	μA
Gate-Body leakage current	I_{GSS}	$V_{GS}=\pm 20V$ $V_{DS}=0V$			100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu A$	1.0	1.7		

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$					

$V_{DS}=15\text{ V}$ $V_{GS}=10\text{ V}$
 $R_{\theta JC}=10\text{ }^{\circ}\text{C/W}$ $T_c(=15\text{ }^{\circ}\text{C})$ $T_j=385\text{ }^{\circ}\text{C}$ $T_f=330008\text{ }^{\circ}\text{C}$ $T_{57TcTc}(\text{ }^{\circ}\text{C})$ $T_j < 0200$





BR

080N03D

Note:

BR: Company Code

080N03D: Product Type

****: Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|-----------|-------------|---|
| 1 | 150 ~ 180 | 60 ~ 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245..5 | 5..0.5sec; | 2.Peak Temp.:245..5 , Duration:5..0.5sec. |
| 3 | 2 ~ 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

605..5